Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	200			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.19		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 200 V, V _{GS} = 0 V			1	μА
		V _{DS} = 160 V, T _C = 125°C			10	μА
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5 A		0.28	0.36	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 5 A (Note 4)		6.7		S
C _{iss}	Input Capacitance Output Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		510 95	130	pF pF
C _{rss}	Reverse Transfer Capacitance			13	17	pF
Switchi	ing Characteristics					
$t_{d(on)}$	Turn-On Delay Time	V _{DD} = 100 V, I _D = 10 A,		13	40	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$		90	190	ns
t _{d(off)}	Turn-Off Delay Time			26	70	ns
t _f	Turn-Off Fall Time	(Note 4, 5)	50	110	ns
Qg	Total Gate Charge	V _{DS} = 160 V, I _D = 10 A,		13.5	18	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V		3.8		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)	5.5		nC
Drain-S	Source Diode Characteristics ar	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				10	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				40	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 10 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 10 A,		130		ns

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 2.7mH, I_{AS} = 10A, V_{DD} = 50V, R_G = 25 Ω . Starting T_J = 25°C 3. I_{SD} \leq 10A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300 μ s, Duty cycle \leq 2% 5. Essentially independent of operating temperature

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Typical Characteristics

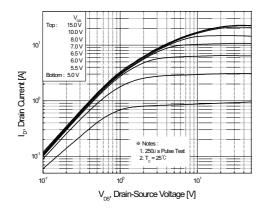


Figure 1. On-Region Characteristics

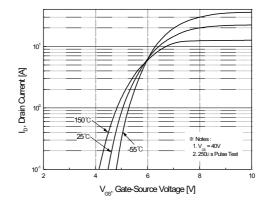


Figure 2. Transfer Characteristics

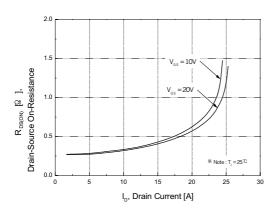


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

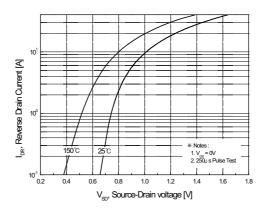


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

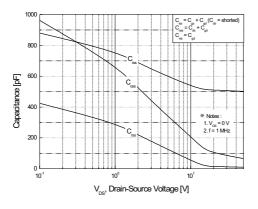


Figure 5. Capacitance Characteristics

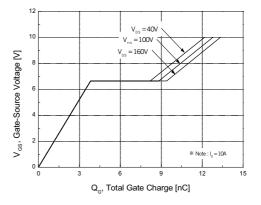
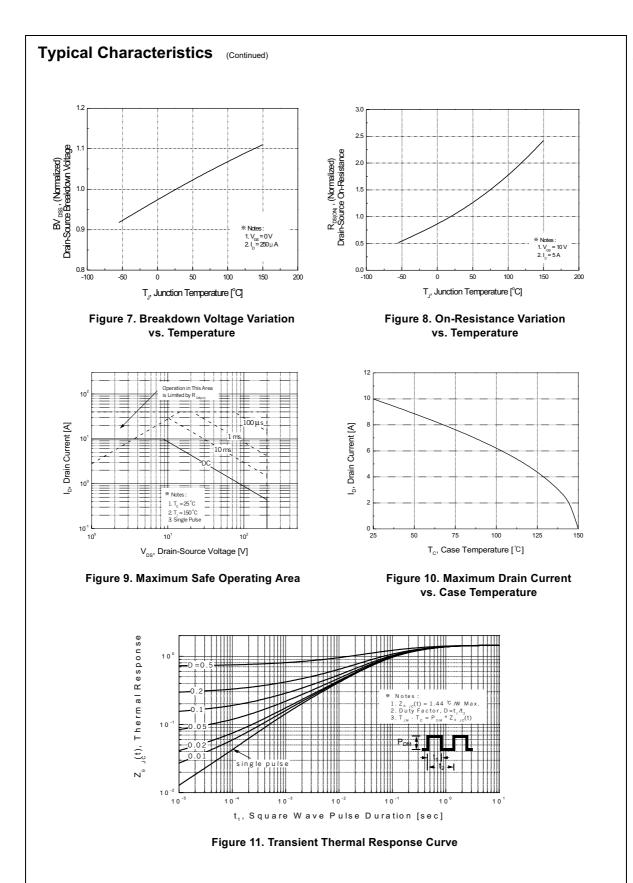


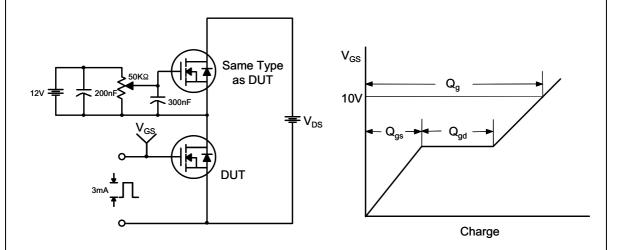
Figure 6. Gate Charge Characteristics

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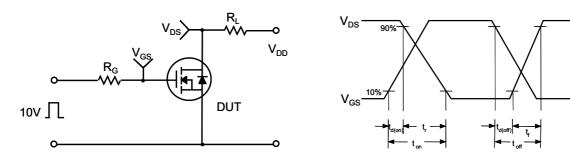


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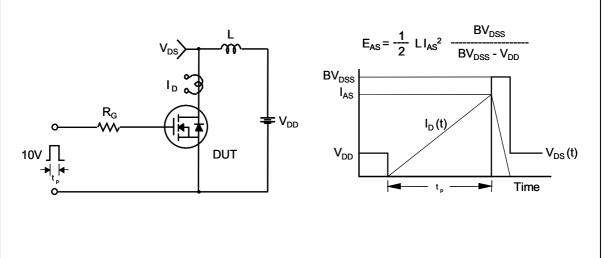
Gate Charge Test Circuit & Waveform



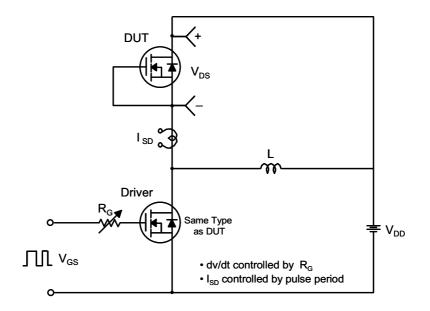
Resistive Switching Test Circuit & Waveforms

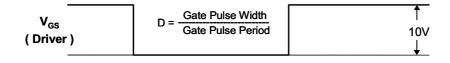


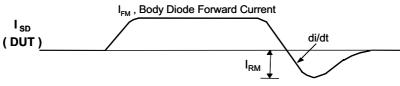
Unclamped Inductive Switching Test Circuit & Waveforms



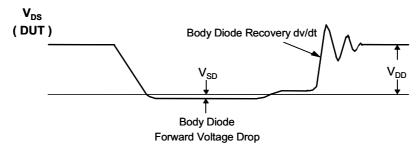
Peak Diode Recovery dv/dt Test Circuit & Waveforms



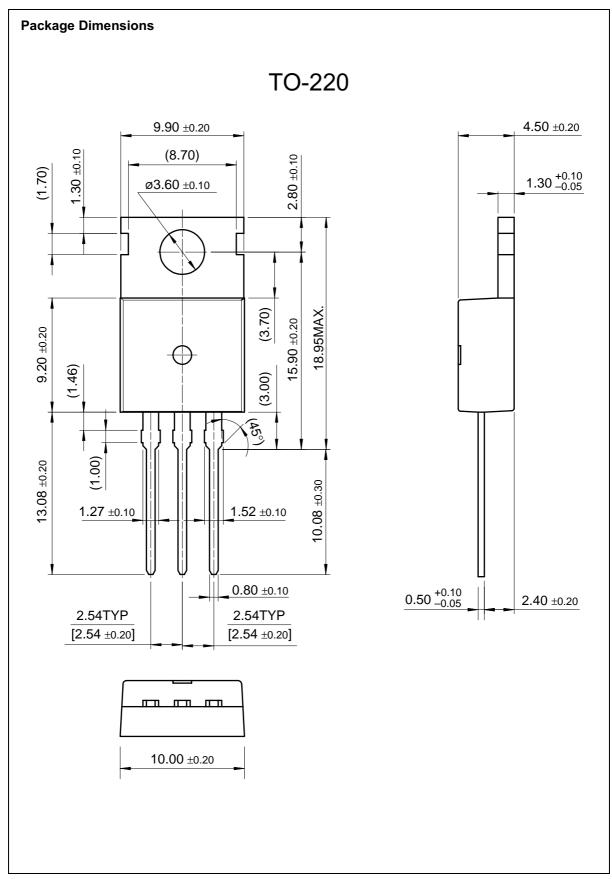




Body Diode Reverse Current



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